

# GP1S196HCZ0F GP1S196HCZSF

Gap : 1.1mm, Slit : 0.3mm  
Phototransistor Output,  
Compact Transmissive  
Photointerrupter



## ■ Description

**GP1S196HCZ0F** is a compact-package, photo-transistor output, transmissive photointerrupter, with opposing emitter and detector in a molding that provides non-contact sensing. The compact package series is a result of unique technology combining transfer and injection molding.

This device is half the size of the rest of the parts in this family.

## ■ Features

1. Transmissive with phototransistor output
2. Highlights :
  - Compact Size
  - Low Profile
  - Narrow Gap
  - Through-hole : **GP1S196HCZ0F**
  - SMT : **GP1S196HCZSF**
3. Key Parameters :
  - Gap Width : 1.1mm
  - Slit Width (detector side): 0.3mm
  - Package : 3.1×2×2.7mm
4. RoHS directive compliant

## ■ Agency approvals/Compliance

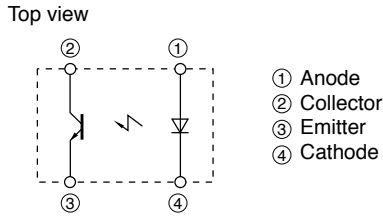
1. Compliant with RoHS directive

## ■ Applications

1. General purpose detection of object presence or motion.
2. Example : printer, lens control for camera

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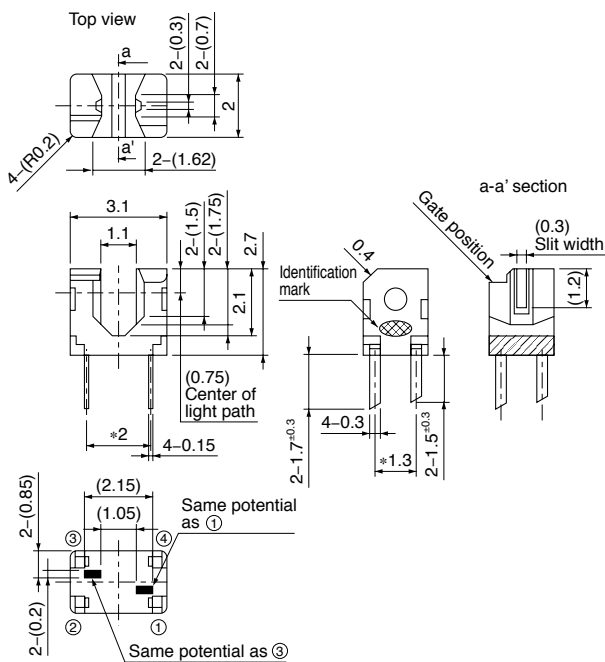
## Internal Connection Diagram



## Outline Dimensions

(Unit : mm)

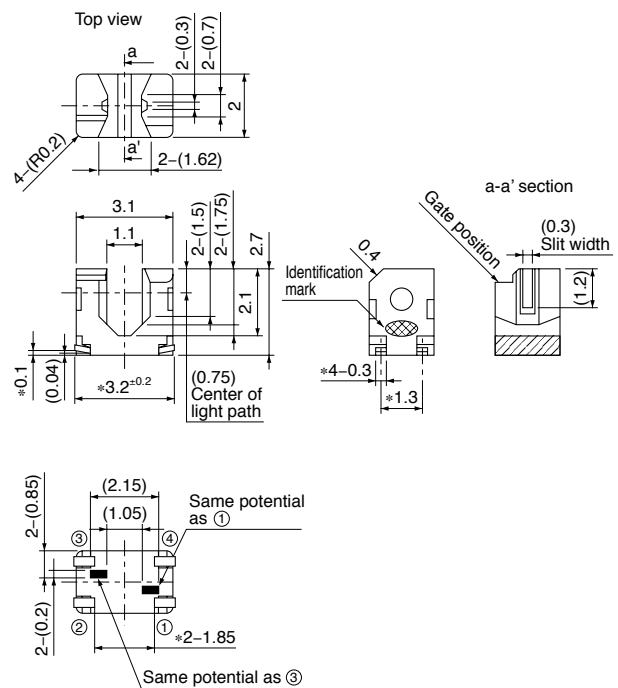
### Through-Hole [GP1S196HCZ0F]



- Unspecified tolerance :  $\pm 0.1$ mm.
- Dimensions in parenthesis are shown for reference.
- The dimensions indicated by \* refer to those measured from the lead base.
- The dimensions shown do not include those of burrs.  
Burr's dimensions : 0.15mm MAX.
- The lead may be exposed at the painting out portion.
- There is agreeer identification mark on he light emitting side.

Product mass : approx. 0.022g

### SMT Gullwing Lead-Form [GP1S196HCZ0F]



- Unspecified tolerance :  $\pm 0.1$ mm.
- Dimensions in parenthesis are shown for reference.
- The dimensions indicated by \* refer to those measured lead plating portion.
- The dimensions shown do not include those of burrs.  
Burr's dimensions : 0.15mm MAX.
- The lead may be exposed at the painting out portion.
- There is agreeer identification mark on he light emitting side.

Product mass : approx. 0.02g

Plating material : SnCu (Cu : TYP. 2%)

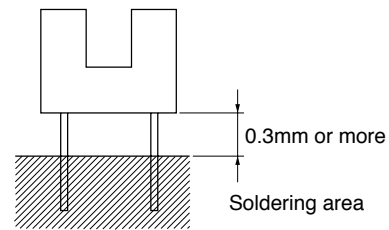
Country of origin

Japan

## ■ Absolute Maximum Ratings (T<sub>a</sub>=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	30	mA
	Reverse voltage	V <sub>R</sub>	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V <sub>CEO</sub>	35	V
	Emitter-collector voltage	V <sub>ECO</sub>	6	V
	Collector current	I <sub>C</sub>	20	mA
	Collector power dissipation	P <sub>C</sub>	75	mW
Total power dissipation		P <sub>tot</sub>	100	mW
Operating temperature		T <sub>opr</sub>	-25 to +85	°C
Storage temperature		T <sub>stg</sub>	-40 to +100	°C
*1 Soldering temperature		T <sub>sol</sub>	260	°C

\*1 For 3s or less

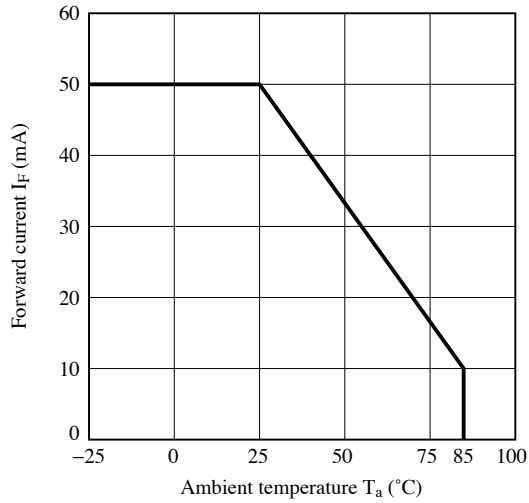


(GP1S196HCZ0F)

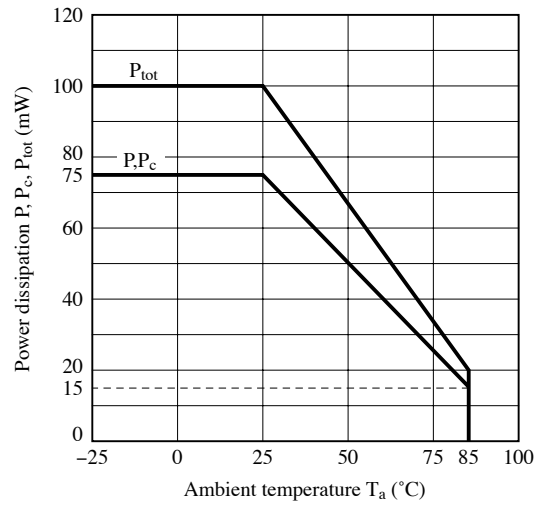
## ■ Electro-optical Characteristics (T<sub>a</sub>=25°C)

Parameter		Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	-	1.2	1.4	V
	Reverse current	I <sub>R</sub>	V <sub>R</sub> =3V	-	-	10	μA
Output	Collector dark current	I <sub>CEO</sub>	V <sub>CE</sub> =20V	-	-	100	nA
Transfer characteristics	Collector current	I <sub>C</sub>	V <sub>CE</sub> =5V, I <sub>F</sub> =5mA	100	-	400	μA
	Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> =10mA, I <sub>C</sub> =40μA	-	-	0.4	V
	Response time	Rise time	t <sub>r</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =100μA, R <sub>L</sub> =1kΩ	-	50	150
Fall time		t <sub>f</sub>	-		50	150	

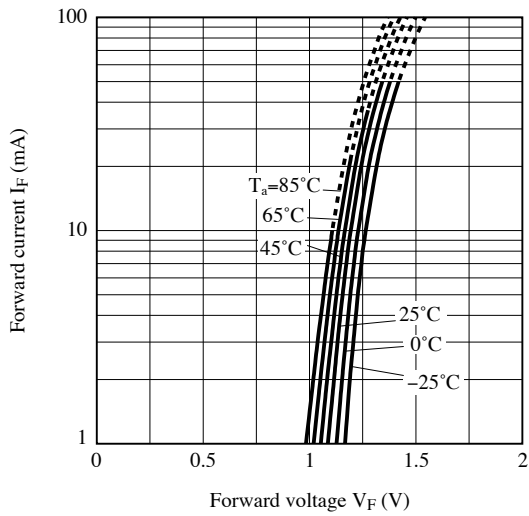
**Fig.1 Forward Current vs. Ambient Temperature**



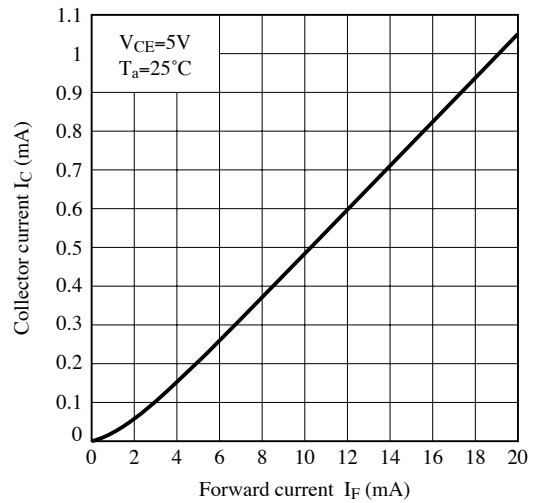
**Fig.2 Power Dissipation vs. Ambient Temperature**



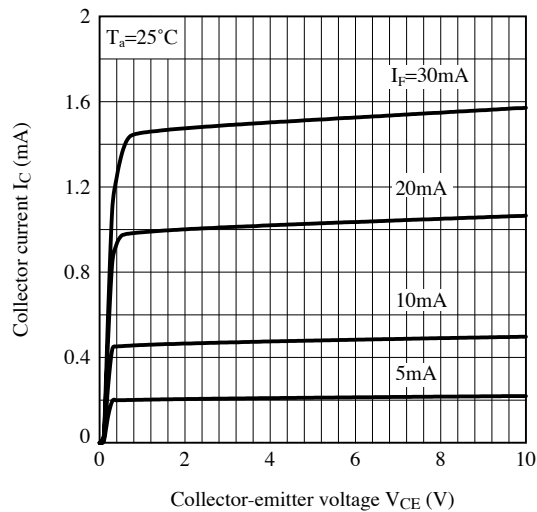
**Fig.3 Forward Current vs. Forward Voltage**



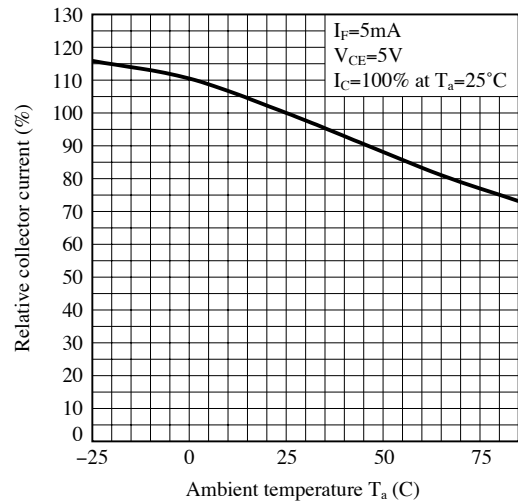
**Fig.4 Collector Current vs. Forward Current**



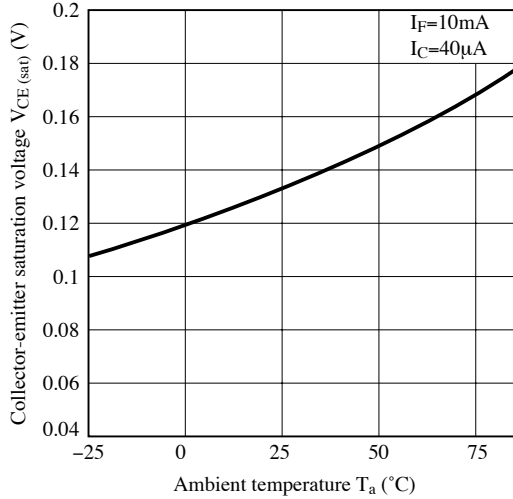
**Fig.5 Collector Current vs. Collector-emitter Voltage**



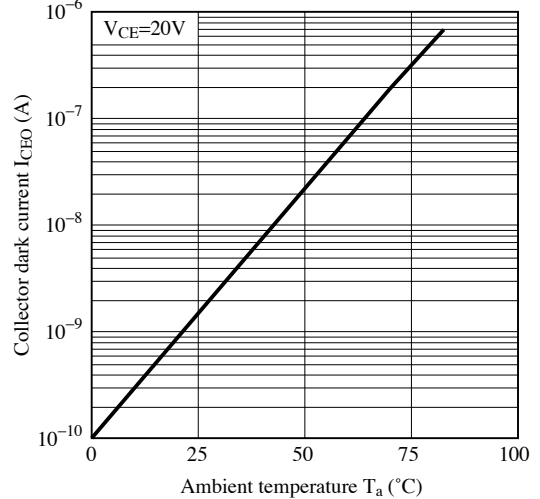
**Fig.6 Relative Collector Current vs. Ambient Temperature**



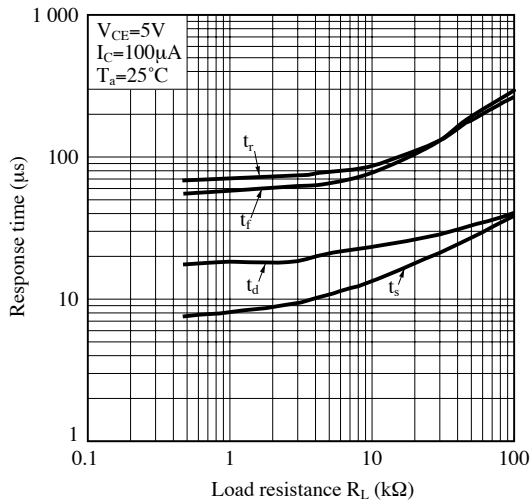
**Fig.7 Collector-emitter Saturation Voltage vs. Ambient Temperature**



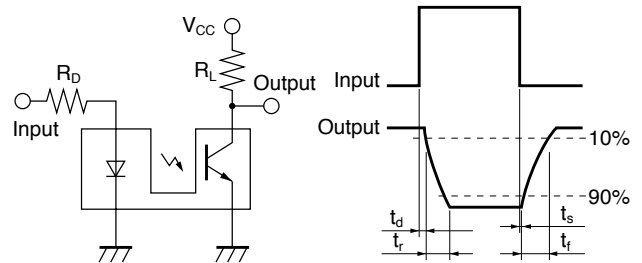
**Fig.8 Collector Dark Current vs. Ambient Temperature**



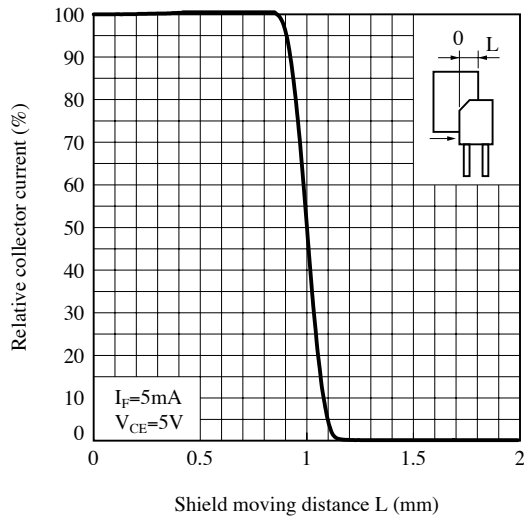
**Fig.9 Response Time vs. Load Resistance**



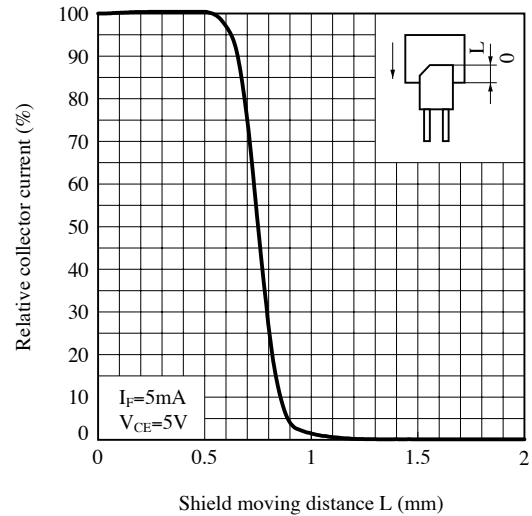
**Fig.10 Test Circuit for Response Time**



**Fig.11 Relative Collector Current vs. Shield Distance (1)**



**Fig.12 Relative Collector Current vs. Shield Distance (1)**



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ **Design Considerations**

● **Design guide**

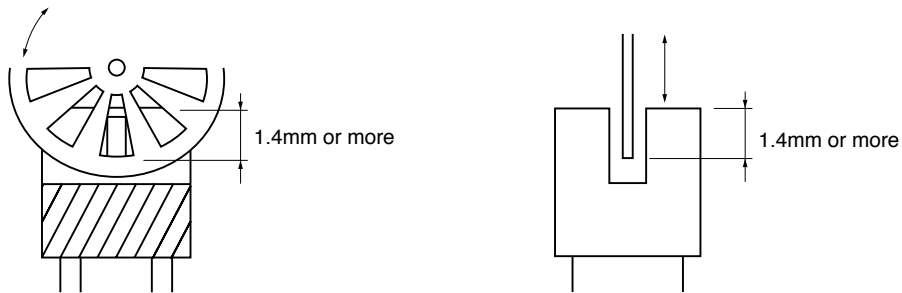
1) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

2) Position of opaque board

Opaque board shall be installed at place 1.4mm or more from the top of elements.

(Example)



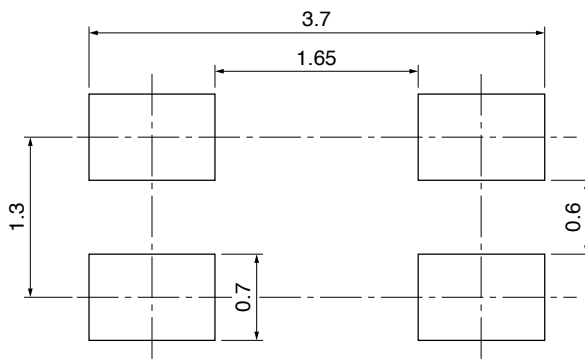
This product is not designed against irradiation and incorporates non-coherent IRED.

● **Degradation**

In general, the emission of the IRED used in photointerrupter will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● **Recommended Foot Print (Only for GP1S196HCZSF)**



● **Parts**

This product is assembled using the below parts.

• **Photodetector (qty. : 1)**

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (μs)
Phototransistor	Silicon (Si)	930	700 to 1 200	20

• **Photo emitter (qty. : 1)**

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

• **Material**

Case	Lead frame	Lead frame plating
Black polyphernylene sulfide resin (UL94 V-0)	42Alloy	SnCu plating

**■ Manufacturing Guidelines**

**● Storage and management after open (Only for GP1S196HCZSF)**

**Storage condition**

Storage temp.: 5 to 30°C, Storage humidity : 70%RH or less at regular packaging.

**Treatment after opening the moisture-proof package**

After opening, you should mount the products while keeping them on the condition of 5 to 25°C and 70%RH or less in humidity within 4 days.

After opening the bag once even if the prolonged storage is necessary, you should mount the products within two weeks.

And when you store the rest of products you should put into a DRY BOX. Otherwise after the rest of products and silicagel are sealed up again, you should keep them under the condition of 5 to 30°C and 70%RH or less in humidity.

**Baking before mounting**

When the above-mentioned storage method could not be executed, please process the baking treatment before mounting the products.

However the baking treatment is permitted within one time.

Recommended condition : 125°C, 16 to 24 hours

\*Do not process the baking treatment with the product wrapped. When the baking treatment processing, you should move the products to a metallic tray or fix temporarily the products to substrate.

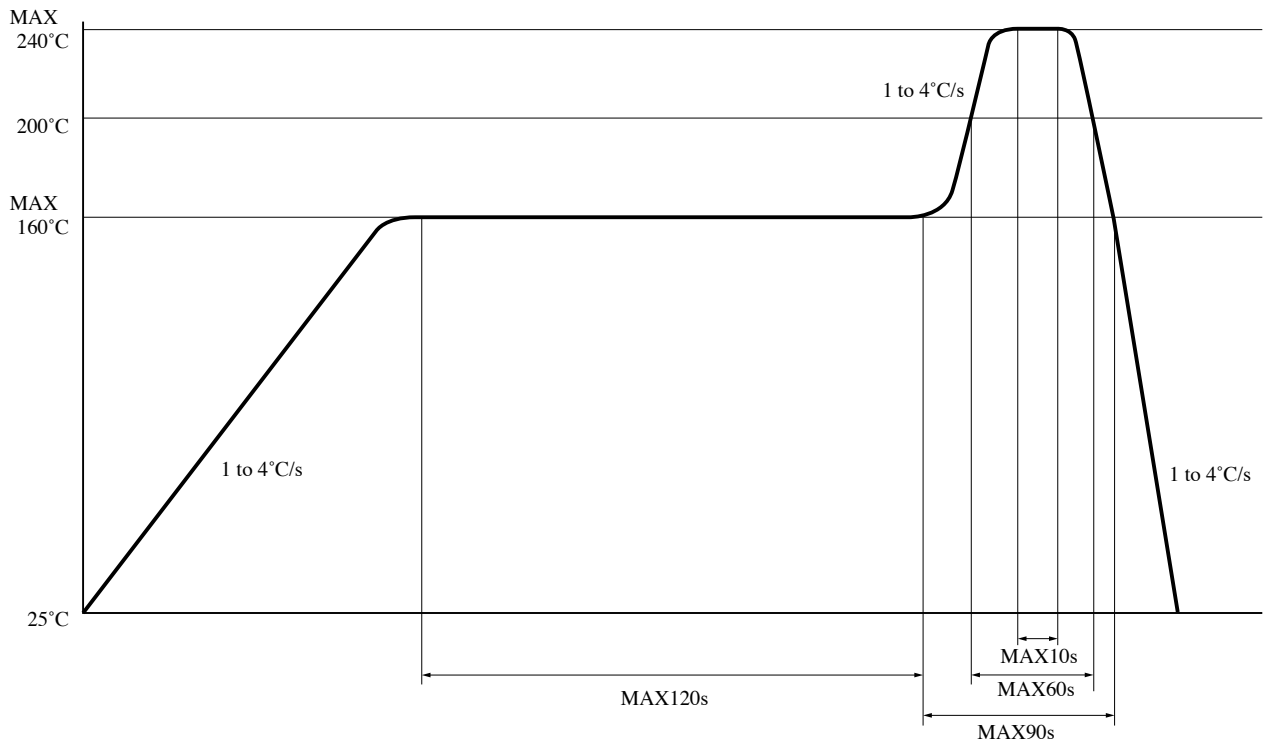
**● Soldering Method**

**Reflow Soldering (Only for GP1S196HCZSF) :**

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please solder within one time.





**Flow Soldering:**

Soldering should be completed below 260°C and within 3 s.

Please solder within one time.

Soldering area is 0.3mm or more away from the bottom of housing.

Please take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

**Other notice**

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the cooling and soldering conditions.

**● Cleaning instructions****Solvent cleaning :**

Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.

**Ultrasonic cleaning :**

Do not execute ultrasonic cleaning.

**Recommended solvent materials :**

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

**● Presence of ODC**

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

**■ Package specification****● Sleeve package****1. Through-hole (GP1S196HCZ0F)****Package materials**

Sleeve : Polycarbonate

Stopper : Styrene-Elastomer

**Package method**

MAX. 200 pcs. of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.

MAX. 50 sleeves in one case.

**2. SMT Gullwing (GP1S196HCZSF)****Package materials**

Sleeve : Polycarbonate

Stopper : Styrene-Elastomer

Aluminium laminated Bag : Nylon, Polyphernylene, Aluminium

**Package method**

MAX. 200 pcs. of products shall be packaged in a sleeve. Both ends shall be closed by tabbed and tabless stoppers.

MAX. 50 sleeves with silicagel are enclosed in aluminium laminated bag. After sealing up the bag, it encased in one case.

**■ Important Notices**

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- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

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- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

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